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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
09/912,064	07/25/2001	Takahiro Oka	TAI 129	3312	
23995 7	7590 12/20/2004		EXAM	EXAMINER	
RABIN & Berdo, PC			ERDEM, FAZLI		
1101 14TH ST	REET, NW				
SUITE 500			ART UNIT	PAPER NUMBER	
WASHINGTO	N, DC 20005		2826		
	,		DATE MAN ED 12/20/200		

DATE MAILED: 12/20/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

			M			
	Application No.	Applicant(s)				
	09/912,064	OKA ET AL.				
Office Action Summary	Examiner	Art Unit				
	Fazli Erdem	2826				
The MAILING DATE of this communication apperiod for Reply	ppears on the cover sheet w	ith the correspondence addres	s			
A SHORTENED STATUTORY PERIOD FOR REP THE MAILING DATE OF THIS COMMUNICATION - Extensions of time may be available under the provisions of 37 CFR 1 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a re - If NO period for reply is specified above, the maximum statutory period - Failure to reply within the set or extended period for reply will, by statu. Any reply received by the Office later than three months after the mail earned patent term adjustment. See 37 CFR 1.704(b).	I. I.136(a). In no event, however, may a eply within the statutory minimum of thi d will apply and will expire SIX (6) MOI ate, cause the application to become A	reply be timely filed rty (30) days will be considered timely. NTHS from the mailing date of this community BANDONED (35 U.S.C. § 133).	nication.			
Status						
1) Responsive to communication(s) filed on 23	September 2004.					
2a)⊠ This action is FINAL . 2b)□ Th	nis action is non-final.					
3) Since this application is in condition for allow	·	•	rits is			
closed in accordance with the practice under	Ex parte Quayle, 1935 C.I	D. 11, 453 O.G. 213.				
Disposition of Claims						
4) ☐ Claim(s) 1 and 3-20 is/are pending in the approach 4a) Of the above claim(s) is/are withdrest 5) ☐ Claim(s) 3,6,8,10,12-16 and 19 is/are allowed 6) ☐ Claim(s) 1,4,9,11,17,18 and 20 is/are rejecte 7) ☐ Claim(s) 5 and 7 is/are objected to. 8) ☐ Claim(s) are subject to restriction and the subject to restrict the subject to restriction and the subject to restrict the subject to restrict	rawn from consideration. d. ed.					
Application Papers						
9)☐ The specification is objected to by the Examir	ner.					
10)☐ The drawing(s) filed on is/are: a)☐ accepted or b)☐ objected to by the Examiner.						
Applicant may not request that any objection to the	e drawing(s) be held in abeya	nce. See 37 CFR 1.85(a).				
Replacement drawing sheet(s) including the corre	· ·					
11) The oath or declaration is objected to by the E	Examiner. Note the attache	a Office Action or form P1O-19	52.			
Priority under 35 U.S.C. § 119						
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority application from the International Bure. * See the attached detailed Office action for a list.	nts have been received. nts have been received in A iority documents have beer au (PCT Rule 17.2(a)).	Application No received in this National Stag	le			
Attachment(s)						
1) Notice of References Cited (PTO-892)		Summary (PTO-413)				
 Notice of Draftsperson's Patent Drawing Review (PTO-948) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08 Paper No(s)/Mail Date 	_ — '	s)/Mail Date nformal Patent Application (PTO-152))			

Application/Control Number: 09/912,064

Art Unit: 2826

Allowable Subject Matter

1. Claims 3, 6, 8, 10, 12-16 and 19 allowed.

The following is a statement of reasons for the indication of allowable subject matter:

Prior art failed to establish semiconductor chip package with the adhesive sheet in the required manner.

2. Claims 5 and 7 objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

The following is a statement of reasons for the indication of allowable subject matter:

Prior art failed to establish the required sunken region on the substrate.

Claim Rejections - 35 USC § 103

- 3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 4. Claims 1,4, 9, 11, 17, 18 and 20 rejected under 35 U.S.C. 103(a) as being unpatentable over Tzu (6,201,302) in view of Kim et al. (KR 2002042958) further in view of Rolda, Jr. et al. (2002/0030261).

Regarding Claims 1,4, 9, 11, 17, 18 and 20, Tzu discloses semiconductor package having multi-dies where in Fig. 3, semiconductor dies 306 and 312 are mounted on the substrate 302 with wiring 310 connecting the semiconductor dies to the substrate. As the

figure shows the semiconductor substrate 302 has an opening larger than the lower die 312 but smaller than the upper die 306. Tzu fails to disclose the required insulating reverse side mounting of the upper and the lower semiconductor ships and the interposer between the two dies. However, Kim et al. disclose stacked chip package where chip 32 is mounted on chip 42 in a reverse manner that is the non-electrode sides are facing each other. Furthermore, Rolda, Jr. et al. disclose a multi-flip-chip semiconductor assembly where in Fig 1, the element 12 that is between the semiconductor chips 110 and 130 is an insulating interposer.

It would have been obvious to one of having ordinary skill in the art at the time the invention was made to include the required reverse manner stacking of upper and lower semiconductor chips and insulating interposer between the upper and the lower semiconductor dies in Tzu as taught by Kim et al. and Rolda, Jr. et al. respectively, in order to have a semiconductor packaging structure with higher reliability.

Conclusion

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37

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CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Fazli Erdem whose telephone number is (571) 272-1914. The examiner can normally be reached on M - F 8:00 - 5:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nathan Flynn can be reached on (571) 272-1915. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

FE December 11, 2004